

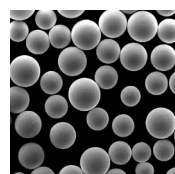


Welco™ AP520 Water Soluble SAC305 T7 and T6 Paste

Welco™ AP520 SAC305 paste is a state-of-the-art water-soluble printing paste, available in both T7 and T6. It is engineered for fine-pitch component and flip chip attach in System-in-Package applications. Featuring excellent stencil opening paste release, no splashing and minimal voids performance over its long work life. These pastes enables all-in-one printing of passive components and flip chips in a single step.

Key Features

- Best-in-class low voids
- No splashing or beading
- Uses high-quality Welco™ powders
- Pure DI water cleanable
- Consistent paste release at 55um stencil opening for T7 and 90um stencil opening for T6



Welco™ Powder



Flux System



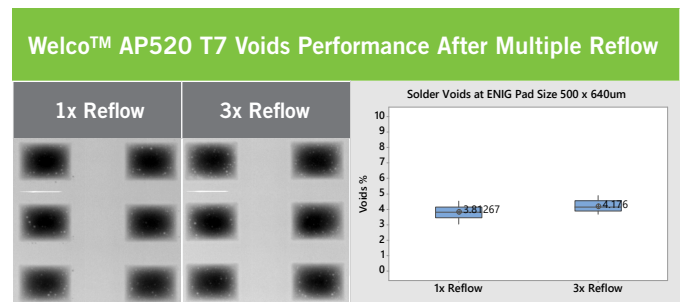
Welco™ AP520 Paste

Welco™ AP520 T7 Continuous Printing Stencil Life Test	0H	4H	8H	12H
Square aperture				
Circular aperture				

- Stencil opening = 55µm, Line spacing = 35µm, Stencil thickness = 25µm, Area ratio: 0.55; ENIG surface
- No missing dot or bridging up to 12Hr of continuous printing

Welco™ AP520 T7 Continuous Printing And Staging With 008004 Component Attach			
0H	12H	12H+8H STG+CA	12H+CA 8H STG

- No tombstoning, solder beading or bridging observed up to 12hr of continuous printing and 8hrs staging
- Excellent low void performance of <10% in total



- Consistently low voids after 3x reflow demonstrated for AP520

All-In-One Printing



Benefits:

- Fewer processing steps
- Eliminate flux cost and substrate pre-soldering cost
- Minimize cold joint or incomplete solder formation

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